VCSEL burn in and packaging

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2019 October 17th
PACKAGING customization
BURN IN early stage
How to achieve it?
effectivity & volume
MICRO MODULE
wafer level carrier
silicon, alumina, silicon photonics
laser & micro optics
monitor photodiode
electrical components
BURN IN
WAFFER LEVEL
back end processes
DIE BONDING

soldering, epoxy
flip chip, face up
± 1µm
WIRE BONDING
ball - wedge
wedge - wedge
BSOB
WAFER PROBING

electrical - VA
optical - LIV
spectrum
BURN IN & AGEING
1mA – 750mA
60°C – 160°C
simultaneously 3000 lasers
SINGULATION
dicing saw
Advantages of MM

customization of carrier
early stage burn in or ageing
effective solution for high volume
compact size for wearable electronics
WHO WE ARE
PACKAGING solution partner
MICRO & OPTO electronics
SILICON PHOTONICS
Markets

INDUSTRIAL  durability
AEROSPACE  reliability
DEFENCE  robustness
AUTOMOTIVE  effectivity
HEALTHCARE  accuracy
Complex solution

FEASIBILITY
DESIGN
PROTOTYPING
QUALIFICATION
ASSEMBLY
VOLUME PRODUCTION
Design
Qualification
Manufacturing
CM, OEM, ODM
SERVICES
let US bring YOU SOLUTION